

Data Center Thermal Management Intelligence Service

Understand how artificial intelligence adoption is directly driving a seismic shift in demand, technology and competition

Key Questions Answered

- How compute demand, chip roadmaps and efficiency pursuit will change the architecture of data center cooling? How this differs regionally?
- Will air cooling and liquid cooling co-exist in data centers?
- Which liquid cooling technology will be most adopted in 2030 and why?
- Who are the winning vendors and what are their strategies?
- How chip makers, IT OEMs and hyperscale operators influence the global supply chain?
- What is the status of heat reuse technology and market?

What We Offer

- Comprehensive coverage of the entire thermal management landscape with technical insights and strategic analysis
- Customer-centric analysts with 10+ years of industry experience and multidisciplinary expertise in engineering and strategic analysis
- End-to-end intelligence for focused decision-making
- Best-in-class "Ask an Analyst" service bringing direct access to experts



Data center cooling has never been more critical. With the right strategy it will enable the next wave of IT innovation and build competitive advantage for data center operators. Those who get it wrong will constrain their business growth by missing out on the most capable compute platforms.



Shen Wang

Principal Analyst
Data Center Power & Cooling Systems

SPEAK WITH OUR EXPERTS

Delivering overarching data center cooling insights

Key Deliverables



Market Trackers

Comprehensive tracker on Data Center Thermal Management.



Reports

In-depth Data Center Thermal Management Market Analysis. Trends to Watch insights.



Briefings

Biannual analyst briefings with research highlights from all market aspects.



Analyst Insights and Access

Ongoing commentary on market shifts and technology developments. Expert analyst support for urgent questions.

Scope of Research

Coverage

- **Product types** including rack, row and direct-to-chip and immersion cooling, chillers, air handling units, and rear door heat exchangers
- **Segmented by heat rejection method:** chilled water, direct evaporative, indirect evaporative, etc.
- **Liquid cooling segmented by fluid:** single phase, two phase
- **Regional splits** for 5 regions and 27 countries
- **Vertical, sales channel and cooling capacity analysis**
- **Vendor market share**, including for specialised vendors and start-ups

Key vendors covered

- Vertiv, Johnson Controls, CoolIT, Stulz, Huawei, Haiwu, Schneider Electric, Zutacore, Submer, etc.

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